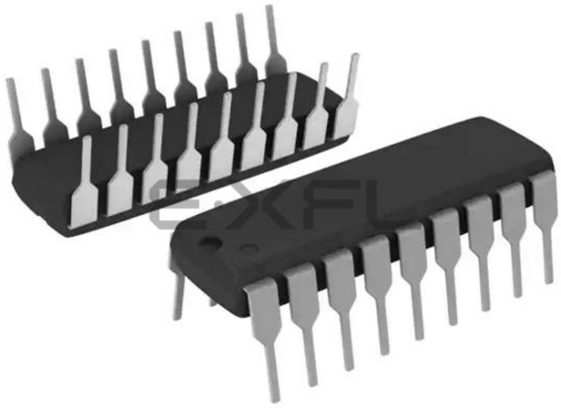

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc620-04i-p

Device Differences

Device	Voltage Range	Oscillator	Process Technology (Microns)
PIC16C620(3)	2.5 - 6.0	See **Note 1**	0.9
PIC16C621(3)	2.5 - 6.0	See **Note 1**	0.9
PIC16C622(3)	2.5 - 6.0	See **Note 1**	0.9
PIC16C620A(4)	2.7 - 5.5	See **Note 1**	0.7
PIC16CR620A(2)	2.5 - 5.5	See **Note 1**	0.7
PIC16C621A(4)	2.7 - 5.5	See **Note 1**	0.7
PIC16C622A(4)	2.7 - 5.5	See **Note 1**	0.7

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

2: For ROM parts, operation from 2.5V - 3.0V will require the PIC16LCR62X parts.

3: For OTP parts, operation from 2.5V - 3.0V will require the PIC16LC62X parts.

4: For OTP parts, operations from 2.7V - 3.0V will require the PIC16LC62XA parts.

4.2 Data Memory Organization

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

FIGURE 4-6: DATA MEMORY MAP FOR THE PIC16C620A/CR620A/621A

File Address			File Address
00h	INDF[1]	INDF[1]	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h–6Fh	General Purpose Register		A0h–F0h
70h–7Fh	General Purpose Register	Accesses 70h-7Fh	F0h–FFh
	Bank 0	Bank 1	

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

FIGURE 4-7: DATA MEMORY MAP FOR THE PIC16C622A

File Address			File Address
00h	INDF[1]	INDF[1]	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h–6Fh	General Purpose Register	General Purpose Register	A0h–BFh
			C0h–F0h
70h–7Fh	General Purpose Register	Accesses 70h-7Fh	F0h–FFh
	Bank 0	Bank 1	

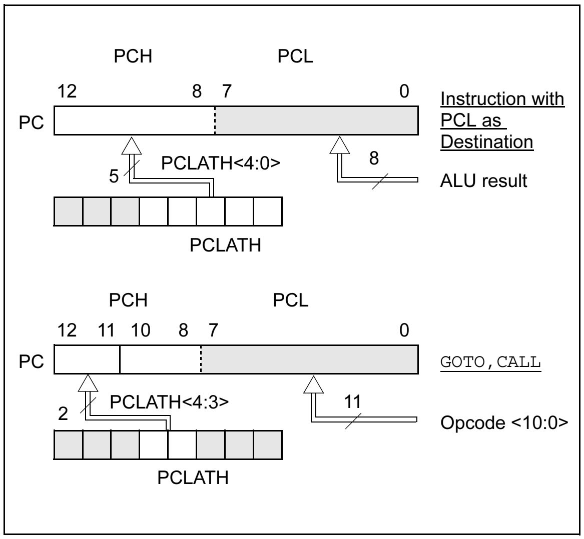
Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any RESET, the PC is cleared. Figure 4-8 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a `CALL` or `GOTO` instruction (PCLATH<4:3> → PCH).

FIGURE 4-8: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (`ADDWF PCL`). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, *"Implementing a Table Read"* (AN556).

4.3.2 STACK

The PIC16C62X family has an 8-level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN`, `RETLW` or a `RETFIE` instruction execution. PCLATH is not affected by a `PUSH` or `POP` operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

> **Note 1:** There are no STATUS bits to indicate stack overflow or stack underflow conditions.
>
> **2:** There are no instructions/mnemonics called `PUSH` or `POP`. These are actions that occur from the execution of the `CALL`, `RETURN`, `RETLW` and `RETFIE` instructions, or the vectoring to an interrupt address.

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The `BCF` and `BSF` instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a `BSF` operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the `BSF` operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Reading the port register reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. `BCF, BSF`, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (ex., `BCF, BSF`, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

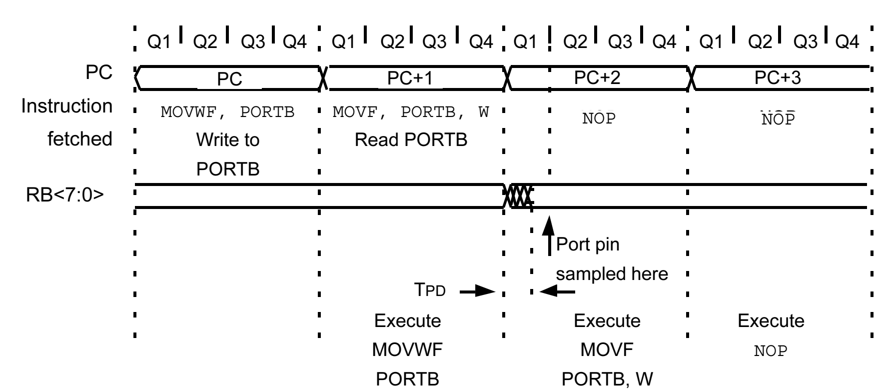
```
; Initial PORT settings:    PORTB<7:4> Inputs
;
;                           PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                           PORT latch   PORT pins
;                           ----------   ---------
                                         -

    BCF  PORTB, 7         ; 01pp pppp    11pp pppp
    BCF  PORTB, 6         ; 10pp pppp    11pp pppp
    BSF  STATUS,RP0       ;
    BCF  TRISB, 7         ; 10pp pppp    11pp pppp
    BCF  TRISB, 6         ; 10pp pppp    10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a `NOP` or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



Note:

This example shows write to PORTB followed by a read from PORTB.

Note that:

data setup time = (0.25 T_{CY} - T_{PD}) where T_{CY} = instruction cycle and TPD = propagation delay of Q1 cycle to output valid.

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

FIGURE 6-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

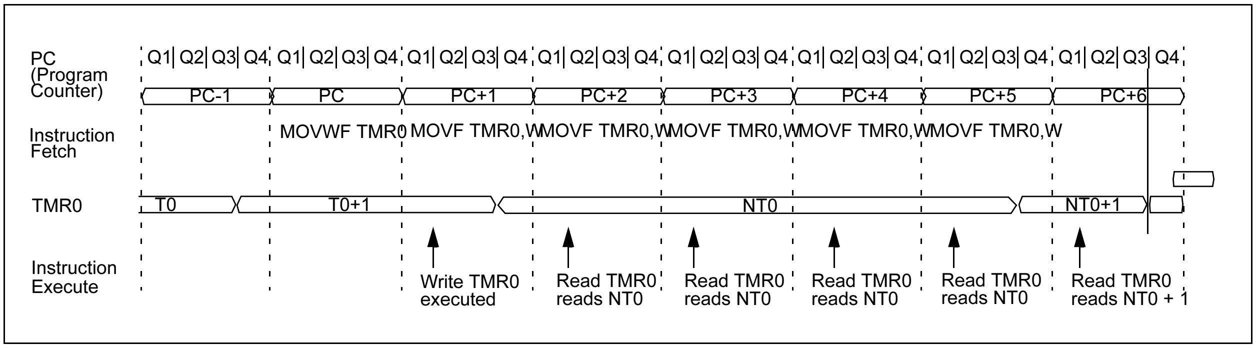
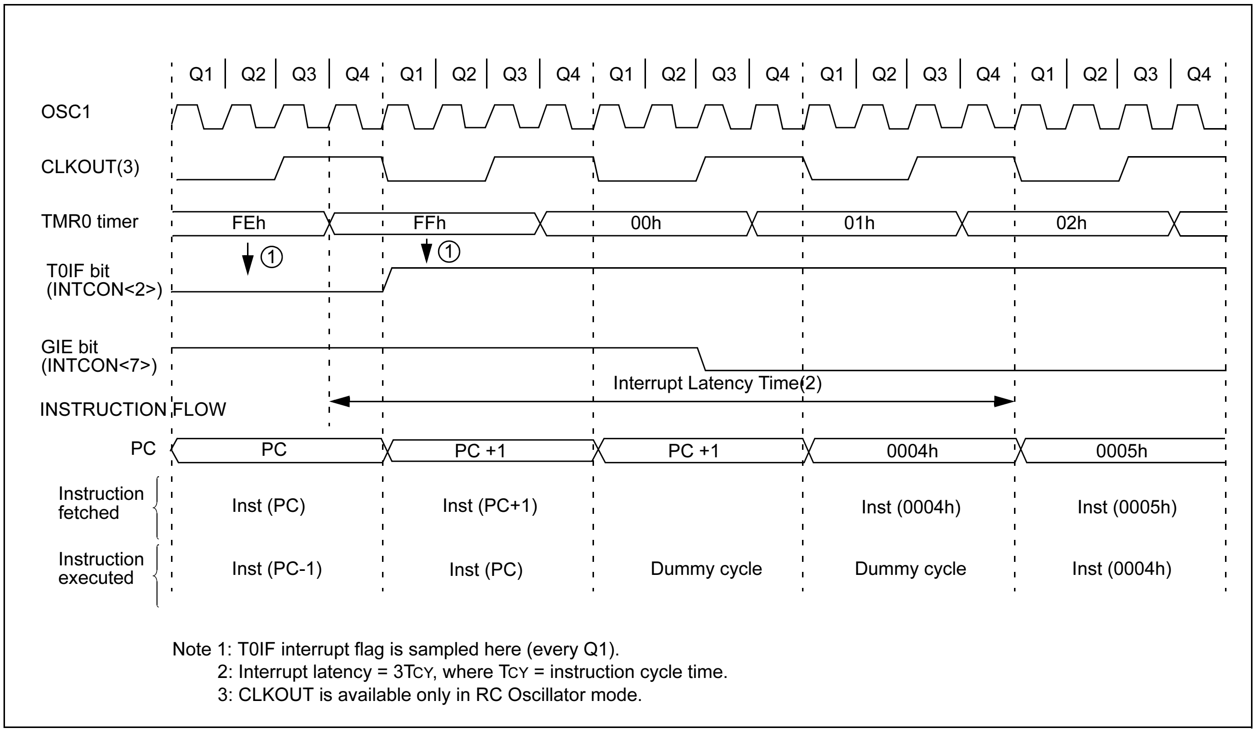


FIGURE 6-4: TIMER0 INTERRUPT TIMING



9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

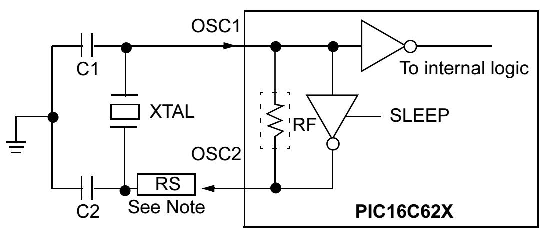
The PIC16C62X devices can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 9-1). The PIC16C62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



See Table 9-1 and Table 9-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

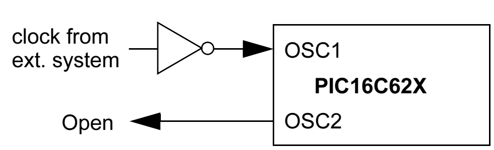


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	**Freq**	**OSC1(C1)**	**OSC2(C2)**
XT	455 kHz 2.0 MHz 4.0 MHz	22 - 100 pF 15 - 68 pF 15 - 68 pF	22 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz 200 kHz	68 - 100 pF 15 - 30 pF	68 - 100 pF 15 - 30 pF
XT	100 kHz 2 MHz 4 MHz	68 - 150 pF 15 - 30 pF 15 - 30 pF	150 - 200 pF 15 - 30 pF 15 - 30 pF
HS	8 MHz 10 MHz 20 MHz	15 - 30 pF 15 - 30 pF 15 - 30 pF	15 - 30 pF 15 - 30 pF 15 - 30 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

PRELIMINARY

9.5.1 RB0/INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP and Figure 9-18 for timing of wake-up from SLEEP through RB0/INT interrupt.

9.5.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 6.0.

9.5.3 PORTB INTERRUPT

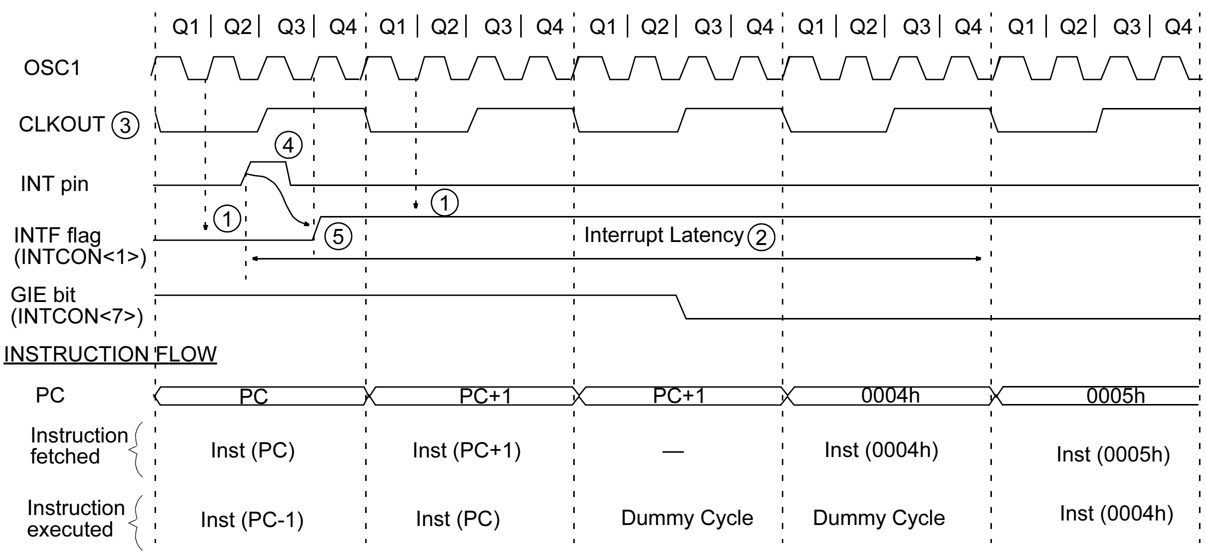
An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

9.5.4 COMPARATOR INTERRUPT

See Section 7.6 for complete description of comparator interrupts.

FIGURE 9-16: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-4 TCY. Synchronous latency = 3 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a two-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

DECFSZ — Decrement f, Skip if 0

Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (dest); skip if result = 0
Status Affected:	None
Encoding:	`00` `1011` `dfff` `ffff`
Description:	The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 0, the next instruction, which is already fetched, is discarded. A `NOP` is executed instead making it a two-cycle instruction.
Words:	1
Cycles:	1(2)

Example

```
HERE      DECFSZ   CNT, 1
          GOTO     LOOP
CONTINUE  •
          •
          •
```

Before Instruction
PC = address `HERE`
After Instruction
CNT = CNT - 1
if CNT = 0,
PC = address `CONTINUE`
if CNT ≠ 0,
PC = address `HERE+1`

GOTO — Unconditional Branch

Syntax:	[*label*] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	k → PC<10:0> PCLATH<4:3> → PC<12:11>
Status Affected:	None
Encoding:	`10` `1kkk` `kkkk` `kkkk`
Description:	`GOTO` is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. `GOTO` is a two-cycle instruction.
Words:	1
Cycles:	2

Example

```
GOTO THERE
```

After Instruction
PC = Address `THERE`

INCF — Increment f

Syntax:	[*label*] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (dest)
Status Affected:	Z
Encoding:	`00` `1010` `dfff` `ffff`
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
Words:	1
Cycles:	1

Example

```
INCF   CNT,  1
```

Before Instruction
CNT = 0xFF
Z = 0
After Instruction
CNT = 0x00
Z = 1

SWAPF	Swap Nibbles in f
Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (dest<7:4>), (f<7:4>) → (dest<3:0>)
Status Affected:	None
Encoding:	`00` | `1110` | `dfff` | `ffff`
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.
Words:	1
Cycles:	1
Example	`SWAPF` REG, 0 Before Instruction REG1 = 0xA5 After Instruction REG1 = 0xA5 W = 0x5A

TRIS	Load TRIS Register
Syntax:	[*label*] TRIS f
Operands:	$5 \le f \le 7$
Operation:	(W) → TRIS register f;
Status Affected:	None
Encoding:	`00` | `0000` | `0110` | `0fff`
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.
Words:	1
Cycles:	1
Example	

To maintain upward compatibility with future PICmicro® products, do not use this instruction.

XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Encoding:	`11` | `1010` | `kkkk` | `kkkk`
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`XORLW 0xAF` Before Instruction W = 0xB5 After Instruction W = 0x1A

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (dest)
Status Affected:	Z
Encoding:	`00` | `0110` | `dfff` | `ffff`
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	`XORWF REG` 1 Before Instruction REG = 0xAF W = 0xB5 After Instruction REG = 0x1A W = 0xB5

11.20 PICDEM 18R PIC18C601/801 Demonstration Board

The PICDEM 18R demonstration board serves to assist development of the PIC18C601/801 family of Microchip microcontrollers. It provides hardware implementation of both 8-bit Multiplexed/De-multiplexed and 16-bit Memory modes. The board includes 2 Mb external FLASH memory and 128 Kb SRAM memory, as well as serial EEPROM, allowing access to the wide range of memory types supported by the PIC18C601/801.

11.21 PICDEM LIN PIC16C43X Demonstration Board

The powerful LIN hardware and software kit includes a series of boards and three PICmicro microcontrollers. The small footprint PIC16C432 and PIC16C433 are used as slaves in the LIN communication and feature on-board LIN transceivers. A PIC16F874 FLASH microcontroller serves as the master. All three microcontrollers are programmed with firmware to provide LIN bus communication.

11.22 PICkit™ 1 FLASH Starter Kit

A complete "development system in a box", the PICkit FLASH Starter Kit includes a convenient multi-section board for programming, evaluation, and development of 8/14-pin FLASH PIC® microcontrollers. Powered via USB, the board operates under a simple Windows GUI. The PICkit 1 Starter Kit includes the user's guide (on CD ROM), PICkit 1 tutorial software and code for various applications. Also included are MPLAB® IDE (Integrated Development Environment) software, software and hardware "Tips 'n Tricks for 8-pin FLASH PIC® Microcontrollers" Handbook and a USB Interface Cable. Supports all current 8/14-pin FLASH PIC microcontrollers, as well as many future planned devices.

11.23 PICDEM USB PIC16C7X5 Demonstration Board

The PICDEM USB Demonstration Board shows off the capabilities of the PIC16C745 and PIC16C765 USB microcontrollers. This board provides the basis for future USB products.

11.24 Evaluation and Programming Tools

In addition to the PICDEM series of circuits, Microchip has a line of evaluation kits and demonstration software for these products.

- KEELOQ evaluation and programming tools for Microchip's HCS Secure Data Products
- CAN developers kit for automotive network applications
- Analog design boards and filter design software
- PowerSmart battery charging evaluation/ calibration kits
- IrDA® development kit
- microID development and rfLab™ development software
- SEEVAL® designer kit for memory evaluation and endurance calculations
- PICDEM MSC demo boards for Switching mode power supply, high power IR driver, delta sigma ADC, and flow rate sensor

Check the Microchip web page and the latest Product Line Card for the complete list of demonstration and evaluation kits.

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range is the PIC16C62X range.				
Param . No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D022 D022A D023 D023A	ΔIWDT ΔIBOR ΔICOMP ΔIVREF	WDT Current(5) Brown-out Reset Current(5) Comparator Current for each Comparator(5) VREF Current(5)	— — — —	6.0 350 — —	20 25 425 100 300	μA μA μA μA μA	VDD=4.0V (125°C) BOD enabled, VDD = 5.0V VDD = 4.0V VDD = 4.0V
D022 D022A D023 D023A	ΔIWDT ΔIBOR ΔICOMP ΔIVREF	WDT Current(5) Brown-out Reset Current(5) Comparator Current for each Comparator(5) VREF Current(5)	— — — —	6.0 350 — —	15 425 100 300	μA μA μA μA	VDD=3.0V BOD enabled, VDD = 5.0V VDD = 3.0V VDD = 3.0V
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended)
PIC16CR62XA-20 (Commercial, Industrial, Extended)
PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 **PIC16CR62XA-20**			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LCR62XA-04			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current(2)	— — — — — —	1.2 500 1.0 4.0 3.0 35	1.7 900 2.0 7.0 6.0 70	mA μA mA mA mA μA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (**Note 4**)* FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (**Note 4**) FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (**Note 6**) FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current(2)	— — —	1.2 400 35	1.7 800 70	mA μA μA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (**Note 4**)* FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (**Note 4**) FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for industrial and 0°C ≤ T_A ≤ +70°C for commercial and -40°C ≤ T_A ≤ +125°C for extended				
PIC16LCR62XA-04			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial and 0°C ≤ T_A ≤ +70°C for commercial and -40°C ≤ T_A ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in Active Operation mode are:
$\overline{OSC1}$ = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD},
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS}.

4: For RC osc configuration, current through R_{EXT} is not included. The current through the resistor can be estimated by the formula: Ir = $V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16CR62XA-04 PIC16CR62XA-20			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LCR62XA-04			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D020	I_{PD}	Power-down Current(3)	— — — —	200 0.400 0.600 5.0	950 1.8 2.2 9.0	nA μA μA μA	V_{DD} = 3.0V V_{DD} = 4.5V* V_{DD} = 5.5V V_{DD} = 5.5V Extended Temp.
D020	I_{PD}	Power-down Current(3)	— — — —	200 200 0.600 5.0	850 950 2.2 9.0	nA nA μA μA	V_{DD} = 2.5V V_{DD} = 3.0V* V_{DD} = 5.5V V_{DD} = 5.5V Extended
D022	ΔI_{WDT}	WDT Current(5)	—	6.0	10 12	μA μA	V_{DD}=4.0V (125°C)
D022A	ΔI_{BOR}	Brown-out Reset Current(5)	—	75	125	μA	$\overline{BOD}$ enabled, V_{DD} = 5.0V
D023	ΔI_{COMP}	Comparator Current for each Comparator(5)	—	30	60	μA	V_{DD} = 4.0V
D023A	ΔI_{VREF}	VREF Current(5)	—	80	135	μA	V_{DD} = 4.0V
D022	ΔI_{WDT}	WDT Current(5)	—	6.0	10 12	μA μA	V_{DD}=4.0V (125°C)
D022A	ΔI_{BOR}	Brown-out Reset Current(5)	—	75	125	μA	$\overline{BOD}$ enabled, V_{DD} = 5.0V
D023	ΔI_{COMP}	Comparator Current for each Comparator(5)	—	30	60	μA	V_{DD} = 4.0V
D023A	ΔI_{VREF}	VREF Current(5)	—	80	135	μA	V_{DD} = 4.0V
1A	F_{OSC}	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures
1A	F_{OSC}	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in Active Operation mode are:
$\overline{OSC1}$ = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD},
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS}.

4: For RC osc configuration, current through R_{EXT} is not included. The current through the resistor can be estimated by the formula: $Ir = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

6: Commercial temperature range only.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA							**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62X/LC62XA/LCR62XA							**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIH	Input High Voltage					
		I/O ports					
D040		with TTL buffer	2.0V 0.25 VDD + 0.8V	—	VDD VDD	V	VDD = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8 VDD	—	VDD		
D042		$\overline{\text{MCLR}}$ RA4/T0CKI	0.8 VDD	—	VDD	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 VDD 0.9 VDD	—	VDD	V	**(Note 1)**
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	VDD = 5.0V, VPIN = VSS
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current**(2, 3) I/O ports (Except PORTA)			±1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	μA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{\text{MCLR}}$	—	—	±5.0	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	IIL	**Input Leakage Current**(2, 3) I/O ports (Except PORTA)			±1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	μA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{\text{MCLR}}$	—	—	±5.0	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	Output Low Voltage					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, +125°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.5 DC CHARACTERISTICS: PIC16C620A/C621A/C622A-40(7) (Commercial) PIC16CR620A-40(7) (Commercial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	FOSC = DC to 20 MHz
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05 *	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.65	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current(2,4)	— — — — — —	1.2 0.4 1.0 4.0 4.0 35	2.0 1.2 2.0 6.0 7.0 70	mA mA mA mA mA μA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT OSC mode, **(Note 4)*** FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT OSC mode, **(Note 4)** FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS OSC mode, **(Note 6)** FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS OSC mode FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS OSC mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP OSC mode
D020	IPD	Power Down Current(3)	— — — —	— — — —	2.2 5.0 9.0 15	μA μA μA μA	VDD = 3.0V VDD = 4.5V* VDD = 5.5V VDD = 5.5V Extended
D022	ΔIWDT	WDT Current(5)	—	6.0	10 12	μA μA	VDD = 4.0V (125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	75	125	μA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	30	60	μA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	80	135	μA	VDD = 4.0V
	ΔIEE Write	Operating Current	—		3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	—		1	mA	
	ΔIEE	Standby Current	—		30	μA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	—		100	μA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.
† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.
4: For RC OSC configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.
5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.
6: Commercial temperature range only.
7: See Section 12.1 and Section 12.3 for 16C62X and 16CR62X devices for operation between 20 MHz and 40 MHz for valid modified characteristics.

FIGURE 12-16: TIMER0 CLOCK TIMING

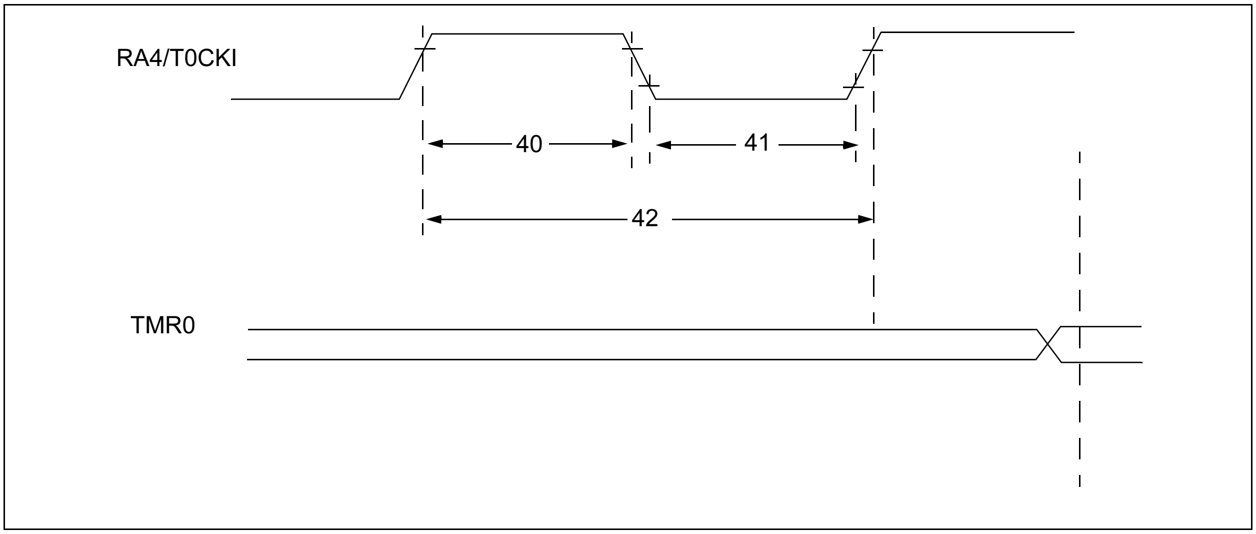


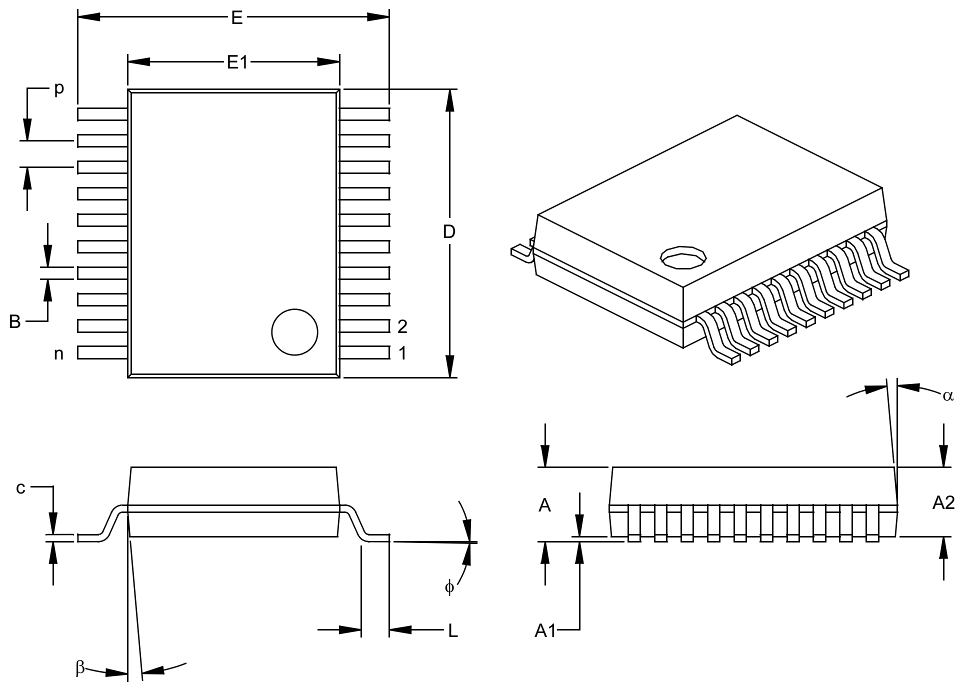
TABLE 12-6: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 T_{CY} + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 T_{CY} + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40^*}{N}$	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

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